

MGC3140 3D Tracking and Gesture Controller Product Brief

Introduction

Microchip's MGC3140 is a 3D gesture and motion tracking controller based on Microchip's patented GestIC[®] technology – suitable for consumer, industrial and automotive applications. It enables robust user interfaces with natural hand and finger movements utilizing the principles of electrical near-field sensing.

Implemented as a low-power mixed-signal configurable controller, the MGC3140 provides a compelling set of smart functional features such as gesture recognition while using adaptive working frequencies for robust performance in noisy environments. Microchip's on-chip Colibri gesture suite removes the need for host post-processing and reduces system power consumption, resulting in low software development efforts for short time-to-market success.

The MGC3140 represents a unique and high-performance single-chip gesture solution focusing on automotive applications. MGC3140 provides proximity, gesture detection and driver recognition, thus enabling modern and compelling user interfaces to be created.

MGC3140 Applications

- Automotive Applications
- IoT
- Audio Products
- Notebooks/Keyboards/PC Peripherals
- Home Automation
- White Goods
- Switches
- Medical Products
- Game Controllers

Power Operation Modes

Several Power Operation Modes Including:

- Processing Mode: 29 mA, typical
- Deep Sleep: 84 µA, typical

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1. Key Features

- Automotive Qualification AEC Q100 Grade 1
- Recognition of 3D Hand Gestures and x, y, z Positional Data
- Proximity and Touch Sensing
- Built-in Colibri Gesture Suite (running on-chip)
- Advanced 3D Signal Processing Unit
- Detection Range: 0 to 10 cm, typical
- Receiver Sensitivity: <1 fF
- Position Rate: 200 positions/sec.
- Spatial Resolution: up to 150 dpi
- Carrier Frequency: 42, 43, 44, 45, 100 kHz
- Channels Supported:
 - Five receive (Rx) channels
 - One transmit (Tx) channel
- On-chip Auto-Calibration
- Low-Noise Radiation due to Low-Transmit Voltage and Slew Rate Control
- Noise Susceptibility Reduction:
 - On-chip analog filtering
 - On-chip digital filtering
 - Automatic frequency hopping
- Enables the use of Low-Cost Electrode Material including:
 - Printed circuit board
 - Conductive paint
 - Conductive foil
 - Laser Direct Structuring (LDS)
 - Touch panel ITO structures
- Field Upgrade Capability
- Operating Voltage: $V_{DD} = 3.3V \pm 5\%$
- Operating Temperature Range: -40°C to +125°C

1.1 **Peripheral Features**

• I²C for Configuration and Sensor Output Streaming I²C, speed up to 400 kHz

2. Functional Description

Microchip Technology's GestIC technology utilizes electrical near-field (E-field) sensing. The chip is connected to electrodes that are sensing the E-field variance. The GestIC device then calculates the user's hand motion relatively to the sensing area in x, y, z position data, and classifies the movement pattern into gestures in real time. In addition, by utilizing the principles of E-field sensing, the GestIC system is immune to ambient influences such as light or sound, which have a negative impact on the majority of other 3D technologies. Also, it allows full-surface coverage of the electrode area with no detection blind spots of a user's action.

Microchip Technology's MGC3140 is a configurable controller. Featuring a Signal Processing Unit (SPU), a wide range of 3D gesture applications are being processed on the MGC3140, which allows short development cycles. Always-on 3D sensing is enabled, even for battery-driven devices, by the chip's low-power design and the variety of programmable power modes. GestIC sensing electrodes are driven by a low-voltage signal with frequencies of 42, 43, 44, 45, and 100 kHz, allowing their electrical conductive structure to be made of any low-cost material. Figure 2-1 provides an overview of the main building blocks of MGC3140.



Figure 2-1. MGC3140 Block Diagram

3. Pin Diagram

Figure 3-1. MGC3140 48L Diagram UQFN



Related Links

4. 48-Pin Allocation and Pinout Description Table

4. 48-Pin Allocation and Pinout Description Table

			mout D	•	
	Pin Number		Buffer Type		
GP5	1	0		Gesture Port 5.	
SYNC	2	0		Gesture device synchronization pulse (every 1 ms).	
DNC	3			not connected	
RX1	4	I	Analog	Analog GestIC [®] input channel 1: Receive electrode connection.	
DNC	5			not connected	
DNC	6			not connected	
MCLR	7	I		Master Clear (Reset) input. This pin is an active-low Reset to the device.	
V _{SS}	8	Р		Ground reference for logic and I/O pins. This pin must be connected at all times.	
V _{DD}	9	Р		Positive supply for peripheral logic and I/O pins.	
IS1	10	I	ST	Interface Selection Pin 1	
IS2	11	I	ST	Interface Selection Pin 2	
RX2	12	I	Analog	Analog GestIC [®] input channel 2: Receive electrode connection.	
DNC	13			not connected	
DNC	14			not connected	
AV _{DD}	15	Р		Positive supply for analog modules. This pin must be connected at all times.	
V _{SS}	16	Р		Ground reference for analog modules.	
V _{ANA}	17	Р		Positive supply for analog front end.	
DNC	18			not connected	
RX3	19	I	Analog	Analog GestIC [®] input channel 3: Receive electrode connection.	
DNC	20			not connected	
DNC	21			not connected	
RX4	22	I	Analog	Analog GestIC [®] input channel 4: Receive electrode connection.	
DNC	23			not connected	
TX0	24	0		GestIC [®] Transmit electrode connection 0.	
TX1	25	0		GestIC [®] Transmit electrode connection 1.	
TX2	26	0		GestIC [®] Transmit electrode connection 2.	
ТХ3	27	0	_	GestIC [®] Transmit electrode connection 3.	
TX4	28	0		GestIC [®] Transmit electrode connection 4.	
SDA	29	I/O	ST	Synchronous serial data input/output for I ² C.	
SCL	30	I/O	ST	Synchronous serial clock input/output for I ² C.	

MGC3140 48-Pin Allocation and Pinout Description Table

Pin Name	Pin Number	Pin Tyne	Buffer Type	Description
V _{DD}	31	P		Positive supply for peripheral logic and I/O pins.
MODE	32	I	ST	Gesture Devices Scan mode: High: 2D touch device measuring; Low: gesture device measuring
TS	33	0		Transfer Status. GestIC [®] message ready interrupt.
V _{SS}	34	Ρ	_	Ground reference for analog modules. This pin must be connected at all times.
DNC	35	—		not connected
DNC	36	_		not connected
PGD	37	I/O	ST	Programming Data line, connect to test pin in application.
PGC	38	I/O	ST	Programming Clock line, connect to test pin in application.
DNC	39			not connected
DNC	40	_		not connected
RX0	41	I	Analog	Analog GestIC [®] input channel 0: Receive electrode connection.
DNC	42	—		not connected
DNC	43			not connected
V _{CORECAP}	44	Р		Capacitor for Internal Voltage Regulator.
GP1	45	0		Gesture Port 1.
GP2	46	0		Gesture Port 2.
GP3	47	0		Gesture Port 3.
GP4	48	0		Gesture Port 4.
Legend:				

Analog = Analog input

P = Power

ST = Schmitt Trigger input with CMOS levels

I = Input

O = Output

I/O = Input/Output

— = N/A

Important: Exposed pad must be connected to V_{SS} .

Related Links

3. Pin Diagram



5. Reference Schematic

Rev. 30-009000A 5/17/2017

6. Packaging Information

Package Marking Information

Legend:	XXX Y YY WW NNN Ie3 *	Customer-specific information or Microchip part number Year code (last digit of calendar year) Year code (last 2 digits of calendar year) Week code (week of January 1 is week '01') Alphanumeric traceability code b- free JEDEC [®] designator for Matte Tin (Sn) This package is Pb-free. The Pb-free JEDEC designator ((e3)) can be found on the outer packaging for this package.
I	be carrie	nt the full Microchip part number cannot be marked on one line, it will d over to the next line, thus limiting the number of available of or customer-specific information.



6.1 Package Details

The following sections give the technical details of the packages.

48-Lead Plastic Ultra Thin Quad Flat, No Lead Package (MV) - 6x6x0.5 mm Body [UQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Microchip Technology Drawing C04-153A Sheet 1 of 2

48-Lead Plastic Ultra Thin Quad Flat, No Lead Package (MV) – 6x6x0.5 mm Body [UQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units		MILLIMETERS		
Dimension	Limits	MIN	NOM	MAX	
Number of Pins	N		48		
Pitch	е		0.40 BSC		
Overall Height	A	0.45	0.50	0.55	
Standoff	A1	0.00	0.02	0.05	
Contact Thickness	A3		0.127 REF		
Overall Width	E		6.00 BSC		
Exposed Pad Width	E2	4.45	4.60	4.75	
Overall Length	D		6.00 BSC		
Exposed Pad Length	D2	4.45	4.60	4.75	
Contact Width	b	0.15	0.20	0.25	
Contact Length	L	0.30	0.40	0.50	
Contact-to-Exposed Pad	K	0.20	-	-	

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.

Package is saw singulated.
 Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-153A Sheet 2 of 2

48-Lead Ultra Thin Plastic Quad Flat, No Lead Package (MV) - 6x6 mm Body [UQFN] With 0.40 mm Contact Length





Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch E		0.40 BSC		
Optional Center Pad Width	W2			4.45
Optional Center Pad Length	T2			4.45
Contact Pad Spacing	C1		6.00	
Contact Pad Spacing	C2		6.00	
Contact Pad Width (X28)	X1			0.20
Contact Pad Length (X28)	Y1			0.80
Distance Between Pads	G	0.20		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2153A

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